Schottky Barrier Diode

NSR0240P2

Schottky barrier diodes are optimized for very low forward voltage drop and low leakage current and are used in a wide range of dc-dc converter, clamping and protection applications in portable devices. NSR0240P2 in a SOD-923 miniature package enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Very Low Forward Voltage Drop 460 mV @ 100 mA
- Low Reverse Current 0.2 μA @ 25 V VR
- 200 mA of Continuous Forward Current
- Power Dissipation of 240 mW with Minimum Trace
- Very High Switching Speed
- Low Capacitance CT = 7 pF
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- This is a Pb-Free Device

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	40	V
Forward Current (DC)	IF	200	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	2.0	Α
ESD Rating: Human Body Model Machine Model	ESD	Class 1C Class A	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

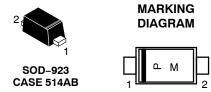


ON Semiconductor®

www.onsemi.com

40 V SCHOTTKY BARRIER DIODE





= Specific Device Code

M = Month Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR0240P2T5G	SOD-923 (Pb-Free)	8000 / Tape & Reel
NSVR0240P2T5G	SOD-923 (Pb-Free)	8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR0240P2

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			520 240	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			175 710	°C/W mW
Junction and Storage Temperature Range	T _J , T _{stg}			-55 to +150	°C

- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
 Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 25 V) (V _R = 40 V)	I _R		0.2 0.8	0.55 5.0	μΑ
Forward Voltage (I _F = 10 mA) (I _F = 100 mA) (I _F = 200 mA)	V _F		0.34 0.46 0.54	0.365 0.50 0.60	V
Total Capacitance (V _R = 1.0 V, f = 1 MHz)	СТ		7.0		pF

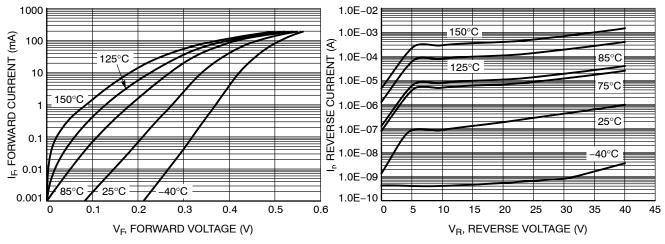


Figure 1. Forward Voltage

Figure 2. Leakage Current

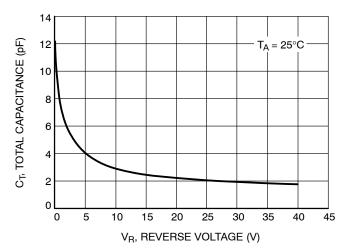
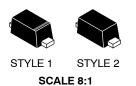


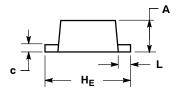
Figure 3. Total Capacitance



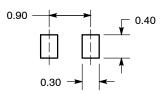
SOD-923 CASE 514AB-01 ISSUE B

DATE 07 MAR 2007

b₂X ⊕ 0.08 (0.0032) X Y



SOLDERING FOOTPRINT*

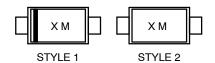


DIMENSIONS: MILLIMETERS

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.34	0.37	0.40	0.013	0.015	0.016	
b	0.15	0.20	0.25	0.006	800.0	0.010	
С	0.07	0.12	0.17	0.003	0.005	0.007	
D	0.75	0.80	0.85	0.030	0.031	0.033	
Е	0.55	0.60	0.65	0.022	0.024	0.026	
HE	0.95	1.00	1.05	0.037	0.039	0.041	
L	0.05	0.10	0.15	0.002	0.004	0.006	

GENERIC MARKING DIAGRAM*



Χ = Specific Device Code = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 2:

STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE

NO POLARITY

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DESCRIPTION:	SOD-923, 1.0X0.6X0.37, MAX HEIGHT 0.40		PAGE 1 OF 1			

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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